PMP4414 BOM 2/12/2014

| Qty | Reference | Description | Size | Value | MFR |
|------|--|--|--|--|---|
| 1 | C20 | Capacitor, Ceramic | 0603 | 0.01uF/25V | STD |
| 1 | C44 | Capacitor, Ceramic | 0603 | 1nF/50V | STD |
| 1 | C22 | Capacitor, Ceramic | 0603 | 1uF/16V | STD |
| 1 | C1 | Capacitor, Ceramic | 0603 | 3.3nF/50V | STD |
| 1 | C50 | Capacitor, Ceramic | 0603 | NA | STD |
| 1 | C7 | CAP CER 1UF 35V X7R 0805 | 0805 | 1uF/35V | STD |
| 1 | C6 | CAP CER 2.2UF 16V X7R 0805 | 0805 | 2.2uF/16V | STD |
| 4 | C2-5 | CAP CER 4.7UF 25V X7R 0805 | 0805 | 4.7uF/25V | STD |
| 1 | J1 | Connector, 100 mil Pitch | | | STD |
| 1 | D3 | DIODE SML SIG 75V 0.15A SOD323F | SOD-323 | 1N4148WS | |
| 1 | U12 | · · · · · | WSON-8 | M25017SD/NOPB | ті |
| 11 1 | | Regulator | | ,, | |
| 1 | T1 | Transformer, MTC-0019SG | | | MNC |
| 1 | R3 | Resistor, Chip, 1/10W, 1% | 0603 | 10K | STD |
| 1 | R34 | Resistor, Chip, 1/10W, 1% | 0603 | 11K | STD |
| 3 | R1-2 R69 | Resistor, Chip, 1/10W, 1% | 0603 | 20K | STD |
| 1 | R5 | Resistor, Chip, 1/10W, 1% | 0603 | 12K | STD |
| 1 | R32 | Resistor, Chip, 1/10W, 1% | 0603 | 240K | STD |
| 1 | R33 | Resistor, Chip, 1/10W, 1% | 0603 | 68K | STD |
| 1 | R4 | Resistor, Chip, 1/10W, 1% | 0603 | NA | STD |
| 2 | D1-2 | DIODE SCHOTTKY 40V 0.4A SOD323 | SOD-323 | ZHCS400 | Infineon |
| 2 | D4-5 | Diode, Zener | SOD-323 | NA | STD |
| | 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 2 | 1 C20 1 C44 1 C22 1 C1 1 C50 1 C7 1 C6 4 C2-5 1 J1 1 D3 1 U12 1 T1 1 R3 1 R34 3 R1-2 R69 1 R32 1 R33 1 R33 1 R4 2 D1-2 | 1 C20 Capacitor, Ceramic 1 C44 Capacitor, Ceramic 1 C22 Capacitor, Ceramic 1 C1 Capacitor, Ceramic 1 C1 Capacitor, Ceramic 1 C1 Capacitor, Ceramic 1 C50 Capacitor, Ceramic 1 C50 Capacitor, Ceramic 1 C7 CAP CER 1UF 35V X7R 0805 1 C6 CAP CER 2.2UF 16V X7R 0805 1 C6 CAP CER 4.7UF 25V X7R 0805 1 J1 Connector, 100 mil Pitch 1 D3 DIODE SML SIG 75V 0.15A SOD323F 1 U12 48 V, 650 mA Constant On-Time Synchronous Buck Regulator 1 T1 Transformer, MTC-0019SG 1 R3 Resistor, Chip, 1/10W, 1% 1 R34 Resistor, Chip, 1/10W, 1% 3 R1-2 R69 Resistor, Chip, 1/10W, 1% 1 R33 Resistor, Chip, 1/10W, 1% 1 R33 Resistor, Chip, 1/10W, 1% 1 R4 Resistor, Chip, 1/10W, 1% 1 R33 | 1 C20 Capacitor, Ceramic 0603 1 C44 Capacitor, Ceramic 0603 1 C22 Capacitor, Ceramic 0603 1 C1 Capacitor, Ceramic 0603 1 C1 Capacitor, Ceramic 0603 1 C50 Capacitor, Ceramic 0603 1 C7 CAP CER 1UF 35V X7R 0805 0805 1 C6 CAP CER 2.2UF 16V X7R 0805 0805 1 D1 Connector, 100 mil Pitch V 1 D3 DIODE SML SIG 75V 0.15A SOD323F SOD-323 1 N1 Connector, MTC-0019SG WSON-8 1 T1 Transformer, MTC-0019SG V 1 R3 Resistor, Chip, 1/10W, 1% 0603 3 R1-2 R69 Resistor, Chip, 1/10W, 1% 0603 < | 1 C20 Capacitor, Ceramic 0603 0.01uF/25V 1 C44 Capacitor, Ceramic 0603 1nF/50V 1 C22 Capacitor, Ceramic 0603 1uF/16V 1 C1 Capacitor, Ceramic 0603 3.3nF/50V 1 C50 Capacitor, Ceramic 0603 NA 1 C7 CAP CER 1UF 35V X7R 0805 0805 1uF/35V 1 C6 CAP CER 2.2UF 16V X7R 0805 0805 2.2uF/16V 4 C2-5 CAP CER 4.7UF 25V X7R 0805 0805 4.7uF/25V 1 J1 Connector, 100 mil Pitch |

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